Line 6, delete "where the element is formed".

Line 7, after "being" insert -- aligned -- ; and change "through hall" to -- elongate opening -- .

Line 8, change "element" to -- chip -- .

Line 9, change "through" to -- elongate opening -- .

Line 10, delete "hall"; and change "through hall" to -- elongate opening -- .

In the Specification

Kindly amend the specification as follows:

Page 1, between lines 3 and 4, insert

--CROSS REFERENCE TO RELATED APPLICATIONS

This is a divisional application of application Serial No. 09/062,720, filed April 20, 1998, now Patent No. 6,175,159 which is hereby incorporated by reference in its entirety for all purposes.--

Page 1, lines 7 and 18, change "device" to -- chip -- .

Page 1, line 7, change "of" (second occurrence) to -- as -- .

Page 1, line 18, change "side of" to -- size as -- .

Page 2, lines 1, 2, 13, and 16, change "element" to -- chip -- .

Page 3, lines 3, 6, 9, 14, and 19, change "element" to -- chip -- .

Page 4, lines 7, 11, 17, 20 and 22, change "element" to -- chip -- .

Page 5, lines 2, 6, 11, 15 and 16, change "element" to -- chip -- .

to use an inexpensive resin substrate instead of an expensive ceramics substrate.

BRIEF DESCRIPTION OF THE DRAWINGS

In the accompanying drawings:

Fig. 1 is a sectional side elevation illustrating a schematic structure of a first embodiment of a semiconductor device according to the present invention;

Fig. 2A and 2B are perspective views of the semiconductor device shown in Fig. 1 for explaining the structure thereof, and particularly, for explaining the rear surface side of a semiconductor package, and Fig. 2C is a perspective view of the semiconductor device shown in Fig. 1 for explaining the structure thereof, and particularly, for explaining the front surface side of the semiconductor package;

Fig. 3 is a perspective view of a semiconductor chip illustrating a surface where the element is formed;

Fig. 4 is a perspective view of the semiconductor device for explaining the rear surface side thereof;

Fig. 5 is a perspective view of the semiconductor device for explaining the rear surface side thereof;

Fig. 6 is a sectional side elevation illustrating a schematic structure of a second embodiment of a semiconductor